

Product Change Notification / RMES-05GWNV962

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23-Jan-2023

Product Category:

Linear Regulators, Power Management - Power Switches

PCN Type:

Manufacturing Change

Notification Subject:

CCB 5127 Final Notice: Qualification of G700 as a new mold compound material for selected MIC20xxx and MIC5159 device families available in 6L SOT-23 package assembled at STAR assembly site.

Affected CPNs:

RMES-05GWNV962_Affected_CPN_01232023.pdf RMES-05GWNV962_Affected_CPN_01232023.csv

Notification Text:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of G700 as a new mold compound material for selected MIC20xxx and MIC5159 device families available in 6L SOT-23 package assembled at STAR assembly site.

Pre and Post Change Summary:

Pre Change Post Change	
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Assembly Site	Stars Microelectronics (Thailand) Public Company Limited	Stars Microelectronics (Thailand) Public Company Limited						
	(STAR)	(STAR)						
Wire Material	Au	Au						
Die Attach Material	84-1LMISR4	84-1LMISR4						
Molding Compound Material	G600	G700						
DAP Surface Prep	NiPdAu with Roughened	NiPdAu with Roughened						
Lead-frame Material	A194	A194						

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change:To improve manufacturability by qualifying G700 as a new mold compound material.

Change Implementation Status:In Progress

Estimated First Ship Date: February 28, 2023 (date code: 2309)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	May 2022			->	January 2023				February 2023							
Workweek	1 9	2	2 1	2 2	2 3		1	2	3	4	5	6	7	8	9	10
Initial PCN Issue Date	Χ															
Qual Report Availability										Χ						
Final PCN Issue Date										Χ						
Estimated Implementation Date															Х	

Method to Identify Change: Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:May 06, 2022: Issued initial notification.

January 23, 2023: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on February 28, 2023.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_RMES-05GWNV962_Qual_Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN</u> home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

MIC2005A-1YM6-TR

MIC2005A-2YM6-TR

MIC2009A-1YM6-TR

MIC2009A-2YM6-TR

MIC2019A-1YM6-TR

MIC2005-0.5YM6-TR

MIC2005-0.8YM6-TR

MIC2005-1.2YM6-TR

MIC2005M-0.5YM6-TR

MIC2007YM6-TR

MIC2008YM6-TR

MIC2009YM6-TR

MIC2015-0.5YM6-TR

MIC2015-0.8YM6-TR

MIC2015-1.2YM6-TR

MIC2017YM6-TR

MIC2018YM6-TR

MIC2019YM6-TR

MIC2019A-2YM6-TR

MIC5159-1.8YM6-TR

MIC5159YM6-TR

Date: Sunday, January 22, 2023